LNJ453W82RA

Hight Bright Surface Mounting Chip LED

SV (Side View) -0.5 Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

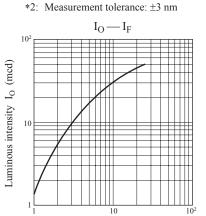
3 "								
Parameter	Symbol	Rating	Unit					
Power dissipation	P _D	55	mW					
Forward current	I _F	20	mA					
Pulse forward current *	I _{FP}	60	mA					
Reverse voltage	V _R	4	V					
Operating ambient temperature	T _{opr}	-30 to +85	°C					
Storage temperature	T _{stg}	-40 to +100	°C					
Note) *: The condition of I _{FP} is duty 10%, Pulse width 1 msec.								

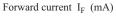
Lighting Color

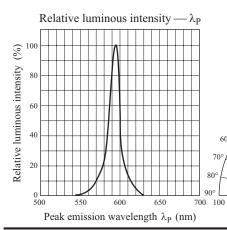
• Amber

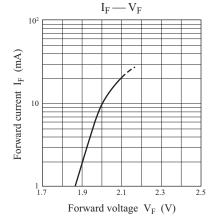
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	6.0	18.0	63.2	mcd
Reverse current	I _R	$V_R = 4 V$			100	μA
Forward voltage	V _F	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 5 \text{ mA}$		595		nm
Dominant emission wavelength *2	λ_d	$I_F = 5 \text{ mA}$	584	589	596	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		15		nm

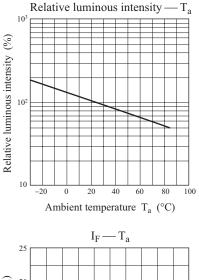
Note) *1: Measurement tolerance: $\pm 20\%$

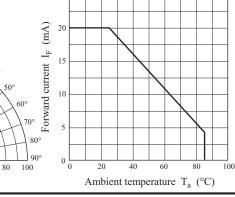












Publication date: November 2011

Relative luminous intensity (%)

Directive characteristics

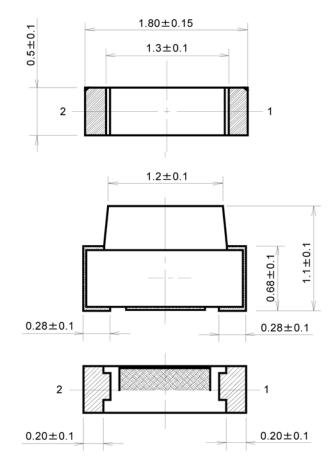
10° 0°

5(

80 60 40 20 0 20 40 60

Package (Unit: mm)

KLTFSN2K5300



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- Pin name
 - 1: Anode
 - 2: Cathode

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